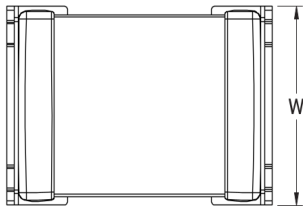
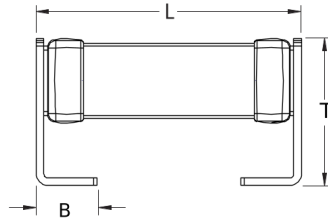


TOP VIEW  
Single or Double Chip Stack



PROFILE VIEW  
Single Chip Stack



Click [here](#) for the 3D model.

### Dimensions

L	3.5mm +/-0.3mm
W	2.6mm +/-0.3mm
T	3.35mm +/-0.10mm
B	0.8mm +/-0.15mm

### Packaging Specifications

Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	600

### General Information

Series	KPS SMD Comm X7R
Style	Stacked Chip
Description	SMD, MLCC, Stacked, Single Chip, Temperature Stable
Features	Temperature Stable
RoHS	Yes
Termination	Tin
AEC-Q200	No
Component Weight	160 mg
Chip Size	1210-1
Shelf Life	78 Weeks
MSL	1

### Specifications

Capacitance	0.1 uF
Measurement Condition	1 kHz 1.0Vrms
Capacitance Tolerance	10%
Voltage DC	250 VDC
Dielectric Withstanding Voltage	625 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	X7R
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kHz 1.0Vrms
Dissipation Factor	2.5% 1kHz 1.0Vrms
Aging Rate	3% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	10 GOhms

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